SCES049C - AUGUST 1995 - REVISED OCTOBER 1996

- Translate Between GTL/GTL+ Signal Levels and LVTTL
- Members of the Texas Instruments *Widebus™* Family

SN74GTL16622 ... DGG PACKAGE

(TOP VIEW)

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19

2

64

61 1B1

OEAB

1A1

GND 3

1A2

1A3

GND

Vcc

1A4

GND

1A5

1A6

GND

1A7

1A8

GND

1A9

2A1

GND

2A2

2A3

GND

2A4

2A5

GND

2A6

Vcc

GND

2A7

2A8

GND

2A9

OEBA

- Support GTL/GTL+ Signal Operation on B Port
- D-Type Flip-Flops With Qualified Storage Enable

CLKAB

63 1CEAB

62 1 1 CEBA

60 GND

59 1B2

58 1B3

57 VCC

56 31B4

55 31B5

54 1B6

53 GND

52 31B7

51 **1B8**

50 GND

49 1B9

48 🛛 2B1

47 🛛 GND

46 2B2

45 2B3

44 🛛 GND

43 🛛 2B4

42 2B5

41 1 2B6

40 VREF

39 2B7

38 2B8

37 GND

36 2B9 35 2CEBA

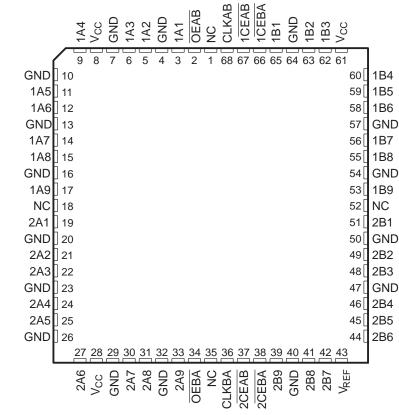
33

34 2CEAB

🛛 CLKBA

- Bus-Hold Data Inputs Eliminate the Need for External Pullup or Pulldown Resistors on A Port
- Flow-Through Architecture Facilitates Printed-Circuit-Board Layout
- Package Options Include Plastic Thin-Shrink Small-Outline (DGG) and Ceramic Quad Flat (HV) Packages

SN54GTL16622...HV PACKAGE (TOP VIEW)



NC - No internal connection



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description

These 18-bit registered bus transceivers contain two sets of D-type flip-flops for temporary storage of data flowing in either direction.

The B port operates at GTL (V_{TT} = 1.2 V and V_{REF} = 0.8 V) and GTL+ (V_{TT} = 1.5 V and V_{REF} = 1 V) levels, while the A port and control inputs are compatible with LVTTL logic levels.

Data flow in each direction is controlled by output-enable (\overline{OEAB} and \overline{OEBA}) and clock (CLKAB and CLKBA) inputs. The clock-enable (\overline{CEAB} and \overline{CEBA}) inputs are designed to control each 9-bit transceiver independently, which makes the device more versatile.

For A-to-B data flow, the devices operate on the low-to-high transition of CLKAB if \overline{CEAB} is low. When \overline{OEAB} is low, the outputs are active. When \overline{OEAB} is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that for A to B, but uses \overline{OEBA} , CLKBA, and \overline{CEBA} .

Active bus-hold circuitry is provided to hold unused or floating TTL inputs at a valid logic state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54GTL16622 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74GTL16622 is characterized for operation from -40° C to 85° C.

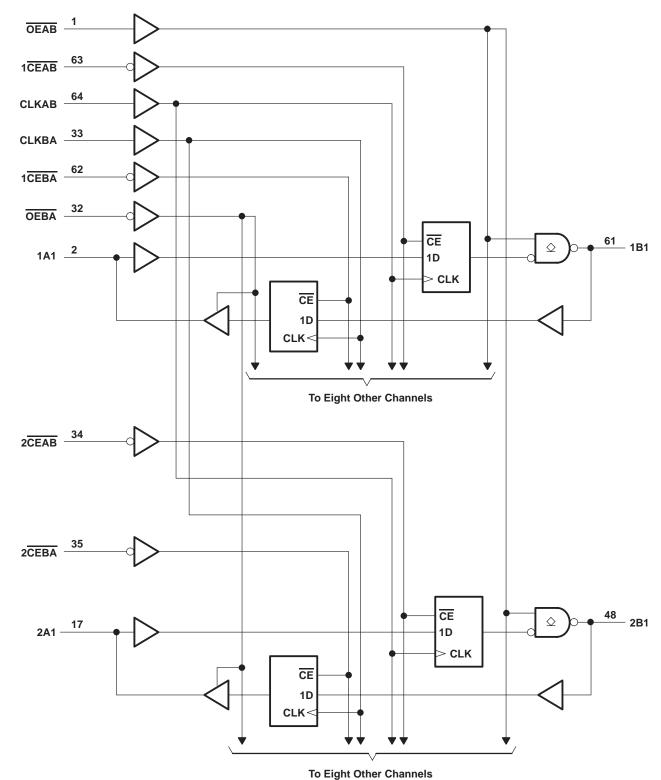
	JN TABLET	-UNCTIC	r				
MODE	OUTPUT	INPUTS					
MODE	В	Α	CLKAB	OEAB	CEAB		
	Z	Х	Х	Н	Х		
	в ₀ ‡	Х	Х	L	Н		
Latched storage of A data	в ₀ ‡ в ₀ ‡	Х	H or L	L	Х		
	L	L	\uparrow	L	L		
Clocked storage of A data	Н	Н	\uparrow	L	L		
					+ • • • •		

[†] A-to-B data flow is shown: B-to-A data flow is similar but uses \overline{OEBA} , CLKBA, and \overline{CEBA} .

[‡]Output level before the indicated steady-state input conditions are established



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logic diagram (positive logic)

Pin numbers shown are for the DGG package.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1): A port/B port Voltage range applied to any output in the high or power-off state, V _O	
(see Note 1): A port/B port	–0.5 V to 4.6 V
Current into any output in the low state, IO: A port	48 mA
B port	100 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I_{OK} (V _O < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DGG package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

 The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 1000 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book.*

UNIT

V

V

V

V

V

V

mΑ

mΑ

mA

°C

SN54GTL16622 SN74GTL16622 MIN NOM MAX MIN NOM MAX Vcc Supply voltage 3.15 3.3 3.45 3.15 3.3 3.45 GTL 1.14 1.2 1.26 1.14 1.2 1.26 Termination VTT voltage GTL+ 1.35 1.5 1.65 1.35 1.5 1.65 GTL 0.74 0.8 0.87 0.74 0.8 0.87 Supply VRFF voltage GTL+ 0.87 1 0.87 1 1.1 1.1 VTT VTT B port 0 0 VI Input voltage Except B port 0 0 Vcc Vcc VREF+50 mV VREF+50 mV B port High-level VIH input voltage Except B port 2 2 V_{REF}-50 mV B port VREF-50 mV Low-level VIL input voltage Except B port 0.8 0.8 Input clamp current -18 -18 IIK High-level A port -24 -24 IOH output current A port 24 24 Low-level output IOL current B port 50 50 ТĄ Operating free-air temperature 125 -40 85 -55

recommended operating conditions (see Note 3)

NOTE 3: Unused control inputs must be held high or low to prevent them from floating.



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PARAMETER			SN54	GTL166	22	SN74GTL16622					
PAR	AMETER	TER TEST CONDITIONS		MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT	
VIK		V _{CC} = 3.15 V,	lj = -18 mA			-1.2			-1.2	V	
		V _{CC} = 3.15 V to 3.45 V,	I _{OH} = -100 μA	V _{CC} -0.2			V _{CC} -0.2				
∨он	A port		I _{OH} = -12 mA	2.4			2.4			V	
		V _{CC} = 3.15 V	I _{OH} = -24 mA	2			2				
		V _{CC} = 3.15 V to 3.45 V,	I _{OL} = 100 μA			0.2			0.2		
	A port		I _{OL} = 12 mA			0.4			0.4		
		V _{CC} = 3.15 V	I _{OL} = 24 mA			0.5			0.5		
VOL		V _{CC} = 3.15 V to 3.45 V,	I _{OL} = 100 μA			0.2			0.2	V	
	Durant		I _{OL} = 10 mA			0.2			0.2		
	в роп	B port	V _{CC} = 3.15 V	I _{OL} = 40 mA			0.4			0.4	
				I _{OL} = 50 mA		RE	0.55			0.55	
lj -	Control inputs	V _{CC} = 3.45 V,	$V_I = V_{CC}$ or GND		C7 P	±5			±5	μA	
'	B port	V _{CC} = 3.45 V,	$V_I = V_{TT}$ or GND	6)	±5			±5	P.	
loff	A port	$V_{CC} = 0$, V_{I} or $V_{O} = 0$ to	3.45 V	2		100			100	μΑ	
	A port		V _I = 0.8 V	75			75				
ll(hold)		A port	V _{CC} = 3.15 V	V _I = 2 V	-75			-75			μA
(/			V _{CC} = 3.45 V [‡] ,	V _I = 0.8 V to 2 V			±500			±500	
IOZH	B port	V _{CC} = 3.45 V,	V _O = 1.5 V			10			10	μΑ	
loz§	A port	V _{CC} = 3.45 V,	$V_{O} = V_{CC}$ or GND			±10			±10	μΑ	
ICC	A or B port	$V_{CC} = 3.45 \text{ V}, I_{O} = 0,$	$V_I = V_{CC} \text{ or } GND$			60			60	mA	
∆I _{CC} ¶	A port or control inputs	V_{CC} = 3.45 V, A port or control inputs at V_{CC} or GND, One input at V_{CC} – 0.6 V				500			500	μA	
Ci	Control inputs	VI = 3.15 V or 0			3			3		pF	
~	A port	V _O = 3.15 V or 0			10			10			
Cio	B port	Per IEEE 1194.1			8.5			8.5		pF	

electrical characteristics over recommended operating free-air temperature range, V_{REF} = 1 V (unless otherwise noted)

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] This is the bus-hold maximum dynamic current required to switch the input from one state to another. § For I/O ports, the parameter I_{OZ} includes the input leakage current.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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timing requirements over recommended ranges of supply voltage and operating free-air temperature for GTL (unless otherwise noted)^{\dagger}

			SN54GTI	16622	SN74GTL	16622	
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	200	0	200	MHz
tw	Pulse duration, CLK high or low		2.5	de la	2.5		ns
	Outras lines	Data before CLK [↑]	3.1	N.M	3		
t _{su}	Setup time	CE before CLK↑	2.8	71.	2.7		ns
	Held Care	Data after CLK [↑]	0.7		0.6		
th	Hold time	CE after CLK↑	0.4		0.3		ns

[†] These parameters are warranted but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature for GTL (see Figure 1)[†]

	FROM	то	SN5	SN54GTL16622		SN7	4GTL16	622	
PARAMETER	(INPUT)	(OUTPUT)	MIN	түр‡	MAX	MIN	TYP‡	MAX	UNIT
fmax			200			200			MHz
^t PLH		В	2.7		6.5	2.8	4.3	6.1	~~
^t PHL	CLKAB	В	1.9		6.2	2	3.6	5.5	ns
^t PLH	0545		2.5	1	6.4	2.6	4.2	6	
^t PHL	OEAB	В	1.6	E	5.8	1.7	3.1	5.1	ns
Slew rate	Both tra	nsitions		0.5			0.5		V/ns
tr	Transition time, B or	utputs (0.6 V to 1 V)	0.5	5	2.6	0.6	1.2	2.5	ns
t _f	Transition time, B or	utputs (1 V to 0.6 V)	0.3	2	2.3	0.4	0.8	2	ns
^t PLH			2.1		5.6	2.2	3.7	5.3	
^t PHL	CLKBA	A	2.2		5.6	2.3	3.8	5.2	ns
t _{en}		•	1.7		5.4	1.8	3.3	5	
^t dis	OEBA	A	2.2		6.2	2.4	4.1	5.7	ns

[†] These parameters are warranted but not production tested.

[‡] All typical values are at V_{CC} = 3.3 V, T_A = 25° C.



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timing requirements over recommended ranges of supply voltage and operating free-air temperature for GTL+ (unless otherwise noted)

			SN54GT	16622	SN74GTI	16622	
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	200	0	200	MHz
tw	Pulse duration, CLK high or low		2.5	6	2.5		ns
	Octors there	Data before CLK↑	2.8	2.4	2.5		
t _{su}	Setup time	CE before CLK↑	2.7	71.	2.6		ns
		Data after CLK1	0.6		0.5		
th	Hold time	CE after CLK↑	0.2		0.1		ns

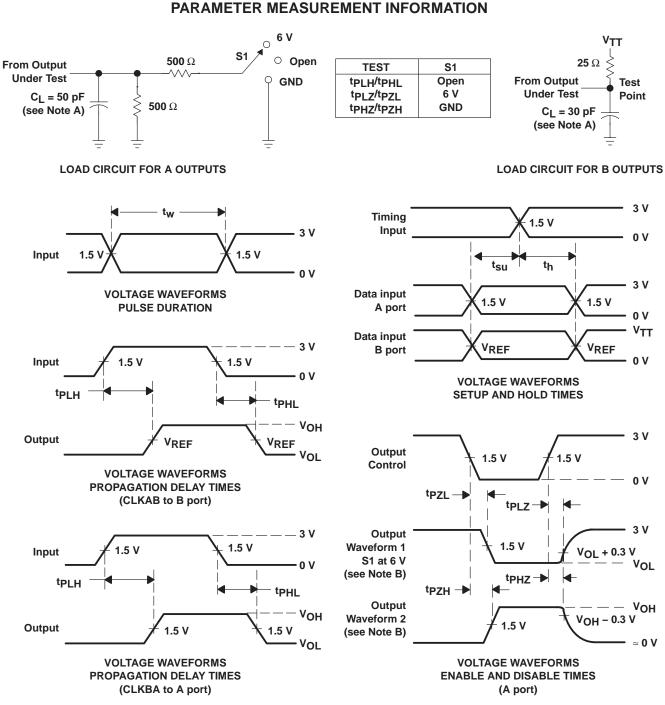
switching characteristics over recommended ranges of supply voltage and operating free-air temperature for GTL+ (see Figure 1)

	FROM	то	SN5	SN54GTL16622		SN7	4GTL16	622	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
f _{max}			200			200			MHz
^t PLH		5	2.8		6.6	2.9	4.2	6.1	
^t PHL	CLKAB	В	2		6.6	2.1	3.7	5.7	ns
^t PLH		5	2.6	4	6.4	2.7	4.1	5.9	
^t PHL	OEAB	В	1.7	Ē	6.1	1.8	3.3	5.3	3 ns
Slew rate	Both tra	nsitions		0.5			0.5		V/ns
tr	Transition time, B ou	tputs (0.6 V to 1.3 V)	0.9	5	3.1	1	1.6	3	ns
t _f	Transition time, B ou	tputs (1.3 V to 0.6 V)	0.6	$\tilde{\mathbf{Q}}$	4.3	0.7	1.4	3.3	ns
^t PLH			2.1		5.6	2.2	3.7	5.3	
^t PHL	CLKBA	A	2.2		5.6	2.3	3.8	5.2	ns
t _{en}			1.6		5.4	1.7	3.2	5	
^t dis	OEBA	A	2.2		6.2	2.4	4.1	5.7	ns

 † All typical values are at V_CC = 3.3 V, T_A = 25°C.



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NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74GTL16622DGGR	OBSOLETE	TSSOP	DGG	64	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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